MC74HC4020A

## 14-Stage Binary Ripple Counter
High–Performance Silicon–Gate CMOS

The MC74C4020A is identical in pinout to the standard CMOS MC14020B. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

This device consists of 14 master–slave flip–flops with 12 stages brought out to pins. The output of each flip–flop feeds the next and the frequency at each output is half of that of the preceding one. Reset is asynchronous and active–high.

State changes of the Q outputs do not occur simultaneously because of internal ripple delays. Therefore, decoded output signals are subject to decoding spikes and may have to be gated with the Clock of the HC4020A for some designs.

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 μA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance With JEDEC Standard No. 7A Requirements
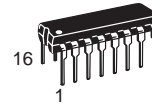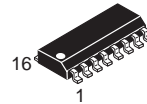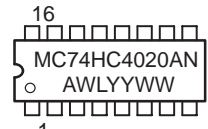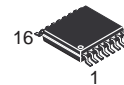- Chip Complexity: 398 FETs or 99.5 Equivalent Gates

ON Semiconductor

http://onsemi.com
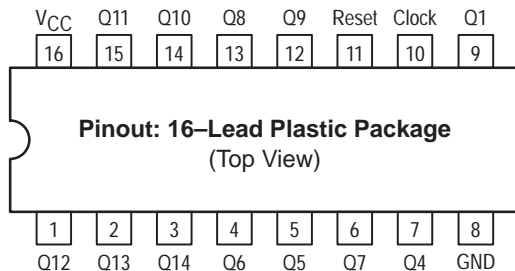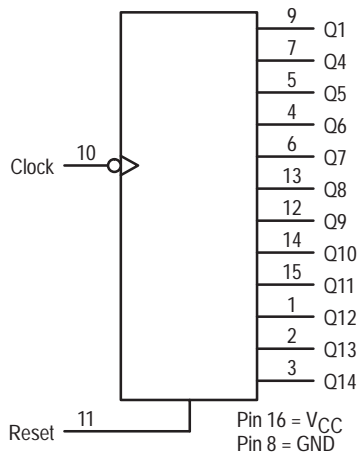
MARKING DIAGRAMS

PDIP–16
N SUFFIX
CASE 648

MC74HC4020AN
AWLYYWW

SO–16
D SUFFIX
CASE 751B

HC4020A
AWLYWW
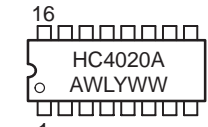
TSSOP–16
DT SUFFIX
CASE 948F
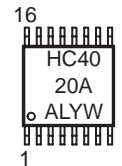
HC40
20A
ALYW

A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

FUNCTION TABLE

Clock	Reset	Output State
⌐_	L	No Charge
‾_	L	Advance to Next State
X	H	All Outputs Are Low

LOGIC DIAGRAM

Pin	Output
9	Q1
7	Q4
5	Q5
4	Q6
6	Q7
13	Q8
12	Q9
14	Q10
15	Q11
1	Q12
2	Q13
3	Q14

Clock 10

Reset 11

Pin 16 = V_CC
Pin 8 = GND

Pinout: 16–Lead Plastic Package (Top View)

V_CC	Q11	Q10	Q8	Q9	Reset	Clock	Q1
16	15	14	13	12	11	10	9

1	2	3	4	5	6	7	8
Q12	Q13	Q14	Q6	Q5	Q7	Q4	GND

ORDERING INFORMATION

Device	Package	Shipping
MC74HC4020AN	PDIP–16	2000 / Box
MC74HC4020AD	SOIC–16	48 / Rail
MC74HC4020ADR2	SOIC–16	2500 / Reel
MC74HC4020ADT	TSSOP–16	96 / Rail
MC74HC4020ADTR2	TSSOP–16	2500 / Reel

March, 2000 – Rev. 2

MC74HC4020A

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	− 0.5 to + 7.0	V
V_{in}	DC Input Voltage (Referenced to GND)	− 0.5 to V_{CC} + 0.5	V
V_{out}	DC Output Voltage (Referenced to GND)	− 0.5 to V_{CC} + 0.5	V
I_{in}	DC Input Current, per Pin	± 20	mA
I_{out}	DC Output Current, per Pin	± 25	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	± 50	mA
P_D	Power Dissipation in Still Air Plastic DIP† SOIC Package† TSSOP Package†	750 500 450	mW
T_{stg}	Storage Temperature Range	− 65 to + 150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds Plastic DIP, SOIC or TSSOP Package	260	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND ≤ (V_{in} or V_{out}) ≤ V_{CC}.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

*Maximum Ratings are those values beyond which damage to the device may occur.
 Functional operation should be restricted to the Recommended Operating Conditions.
†Derating — Plastic DIP: − 10 mW/°C from 65° to 125°C
               SOIC Package: − 7 mW/°C from 65° to 125°C
               TSSOP Package: − 6.1 mW/°C from 65° to 125°C
For high frequency or heavy load considerations, see Chapter 2 of the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)		2.0	6.0	V
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Referenced to GND)		0	V_{CC}	V
T_A	Operating Temperature Range, All Package Types		− 55	+ 125	°C
t_r, t_f	Input Rise/Fall Time (Figure 1)	V_{CC} = 2.0 V V_{CC} = 3.0 V V_{CC} = 4.5 V V_{CC} = 6.0 V	0 0 0 0	1000 600 500 400	ns

DC CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Condition	V_{CC} V	Guaranteed Limit −55 to 25°C	Guaranteed Limit ≤85°C	Guaranteed Limit ≤125°C	Unit
V_{IH}	Minimum High–Level Input Voltage	V_{out} = 0.1V or V_{CC} −0.1V |I_{out}| ≤ 20µA	2.0 3.0 4.5 6.0	1.50 2.10 3.15 4.20	1.50 2.10 3.15 4.20	1.50 2.10 3.15 4.20	V
V_{IL}	Maximum Low–Level Input Voltage	V_{out} = 0.1V or V_{CC} − 0.1V |I_{out}| ≤ 20µA	2.0 3.0 4.5 6.0	0.50 0.90 1.35 1.80	0.50 0.90 1.35 1.80	0.50 0.90 1.35 1.80	V
V_{OH}	Minimum High–Level Output Voltage	V_{in} = V_{IH} or V_{IL} |I_{out}| ≤ 20µA	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		V_{in} = V_{IH} or V_{IL} |I_{out}| ≤ 2.4mA |I_{out}| ≤ 4.0mA |I_{out}| ≤ 5.2mA	3.0 4.5 6.0	2.48 3.98 5.48	2.34 3.84 5.34	2.20 3.70 5.20	
V_{OL}	Maximum Low–Level Output Voltage	V_{in} = V_{IH} or V_{IL} |I_{out}| ≤ 20µA	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		V_{in} = V_{IH} or V_{IL} |I_{out}| ≤ 2.4mA |I_{out}| ≤ 4.0mA |I_{out}| ≤ 5.2mA	3.0 4.5 6.0	0.26 0.26 0.26	0.33 0.33 0.33	0.40 0.40 0.40	

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DC CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Condition	V_{CC} V	Guaranteed Limit			Unit
				−55 to 25°C	≤85°C	≤125°C	
I_{in}	Maximum Input Leakage Current	$V_{in} = V_{CC}$ or GND	6.0	±0.1	±1.0	±1.0	μA
I_{CC}	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC}$ or GND $I_{out} = 0$μA	6.0	4	40	160	μA

NOTE: Information on typical parametric values can be found in Chapter 2 of the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

AC CHARACTERISTICS (C_L = 50 pF, Input t_r = t_f = 6 ns)

Symbol	Parameter	V_{CC} V	Guaranteed Limit			Unit
			−55 to 25°C	≤85°C	≤125°C	
f_{max}	Maximum Clock Frequency (50% Duty Cycle) (Figures 1 and 4)	2.0 3.0 4.5 6.0	10 15 30 50	9.0 14 28 50	8.0 12 25 40	MHz
t_{PLH}, t_{PHL}	Maximum Propagation Delay, Clock to Q1* (Figures 1 and 4)	2.0 3.0 4.5 6.0	96 63 31 25	106 71 36 30	115 88 40 35	ns
t_{PHL}	Maximum Propagation Delay, Reset to Any Q (Figures 2 and 4)	2.0 3.0 4.5 6.0	45 30 30 26	52 36 35 32	65 40 40 35	ns
t_{PLH}, t_{PHL}	Maximum Propagation Delay, Qn to Qn+1 (Figures 3 and 4)	2.0 3.0 4.5 6.0	69 40 17 14	80 45 21 15	90 50 28 22	ns
t_{TLH}, t_{THL}	Maximum Output Transition Time, Any Output (Figures 1 and 4)	2.0 3.0 4.5 6.0	75 27 15 13	95 32 19 15	110 36 22 19	ns
C_{in}	Maximum Input Capacitance		10	10	10	pF

NOTE: For propagation delays with loads other than 50 pF, and information on typical parametric values, see Chapter 2 of the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

* For T_A = 25°C and C_L = 50 pF, typical propagation delay from Clock to other Q outputs may be calculated with the following equations:
V_{CC} = 2.0 V: t_P = [93.7 + 59.3 (n–1)] ns V_{CC} = 4.5 V: t_P = [30.25 + 14.6 (n–1)] ns
V_{CC} = 3.0 V: t_P = [61.5 + 34.4 (n–1)] ns V_{CC} = 6.0 V: t_P = [24.4 + 12 (n–1)] ns

		Typical @ 25°C, V_{CC} = 5.0 V	
C_{PD}	Power Dissipation Capacitance (Per Package)*	38	pF

* Used to determine the no–load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$. For load considerations, see Chapter 2 of the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

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TIMING REQUIREMENTS (Input t_r = t_f = 6 ns)

Symbol	Parameter	V_{CC} V	Guaranteed Limit			Unit
			−55 to 25°C	≤85°C	≤125°C	
t_{rec}	Minimum Recovery Time, Reset Inactive to Clock (Figure 2)	2.0 3.0 4.5 6.0	30 20 5 4	40 25 8 6	50 30 12 9	ns
t_W	Minimum Pulse Width, Clock (Figure 1)	2.0 3.0 4.5 6.0	70 40 15 13	80 45 19 16	90 50 24 20	ns
t_W	Minimum Pulse Width, Reset (Figure 2)	2.0 3.0 4.5 6.0	70 40 15 13	80 45 19 16	90 50 24 20	ns
t_r, t_f	Maximum Input Rise and Fall Times (Figure 1)	2.0 3.0 4.5 6.0	1000 800 500 400	1000 800 500 400	1000 800 500 400	ns

NOTE: Information on typical parametric values can be found in Chapter 2 of the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

PIN DESCRIPTIONS

INPUTS
Clock (Pin 10)

Negative–edge triggering clock input. A high–to–low transition on this input advances the state of the counter.

Reset (Pin 11)

Active–high reset. A high level applied to this input asynchronously resets the counter to its zero state, thus forcing all Q outputs low.

OUTPUTS
Q1, Q4—Q14 (Pins 9, 7, 5, 4, 6, 13, 12, 14, 15, 1, 2, 3)

Active–high outputs. Each Qn output divides the Clock input frequency by 2^N.

SWITCHING WAVEFORMS
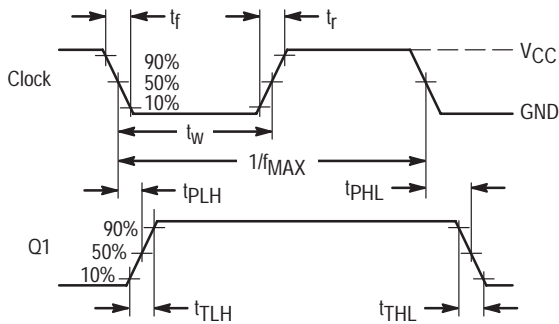
Figure 1.
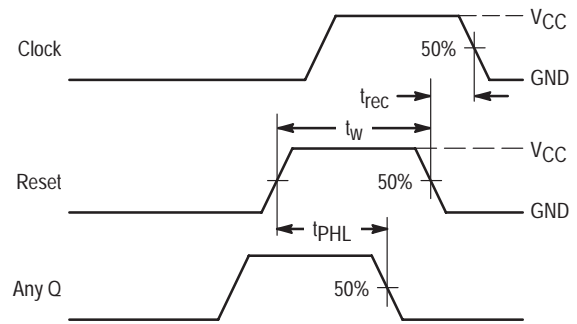
Figure 2.

SWITCHING WAVEFORMS (continued)

Figure 3.
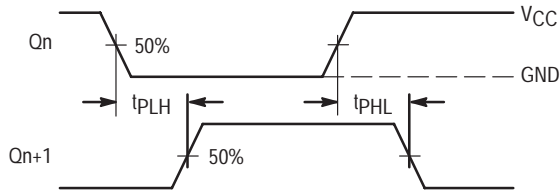
Figure 4. Test Circuit
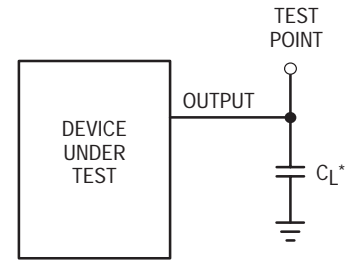
*Includes all probe and jig capacitance

Q6 = Pin 4
Q7 = Pin 6
Q8 = Pin 13

Q9 = Pin 12
Q10 = Pin 14
Q11 = Pin 15

V_{CC} = Pin 16
GND = Pin 8
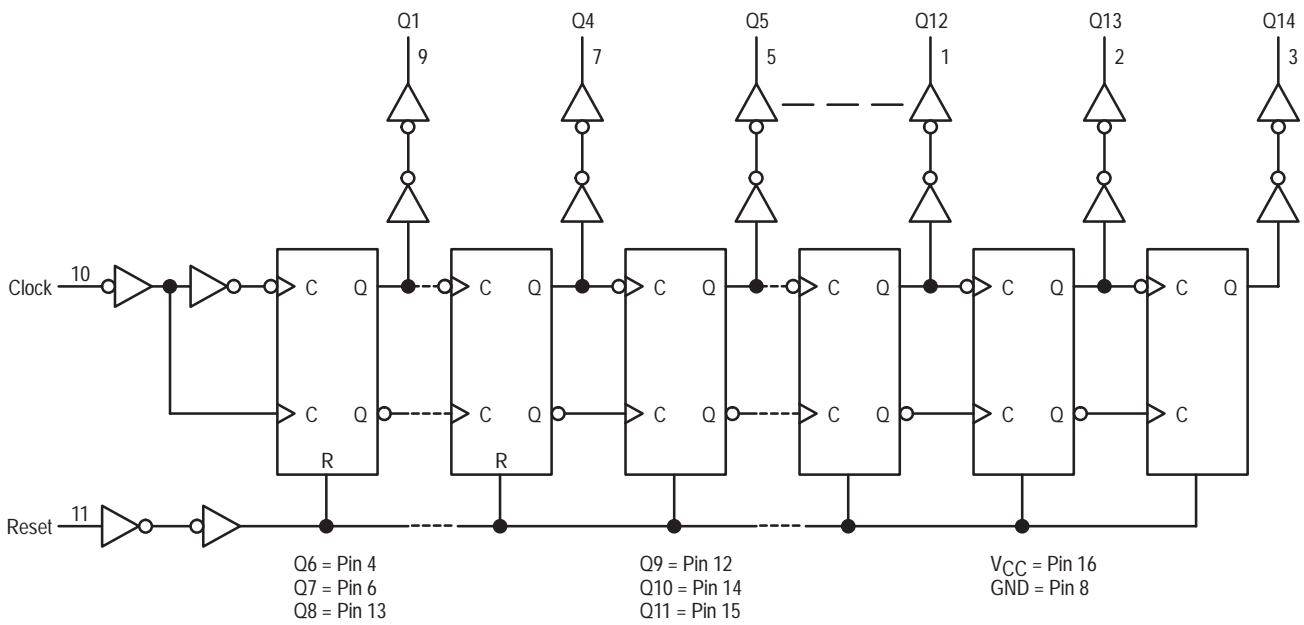
Figure 5. Expanded Logic Diagram

MC74HC4020A
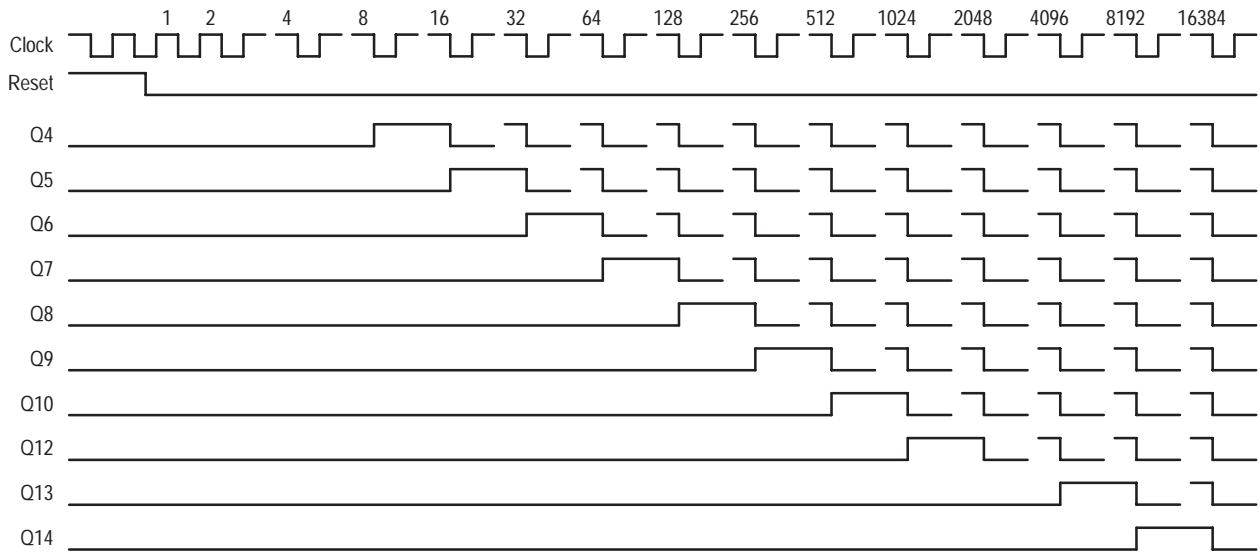
Figure 6. Timing Diagram

APPLICATIONS INFORMATION

Time–Base Generator

A 60Hz sinewave obtained through a 1.0 Megohm resistor connected directly to a standard 120 Vac power line is applied to the input of the MC54/74HC14A, Schmitt-trigger inverter. The HC14A squares–up the input waveform and

feeds the HC4020A. Selecting outputs Q5, Q10, Q11, and Q12 causes a reset every 3600 clocks. The HC20 decodes the counter outputs, produces a single (narrow) output pulse, and resets the binary counter. The resulting output frequency is 1.0 pulse/minute.
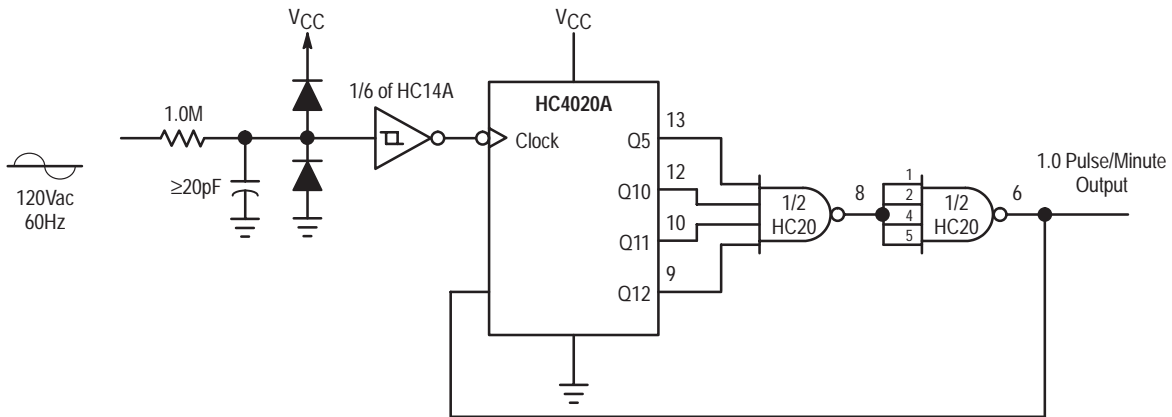
Figure 7. Time–Base Generator

MC74HC4020A

PACKAGE DIMENSIONS

PDIP–16
N SUFFIX
CASE 648–08
ISSUE R
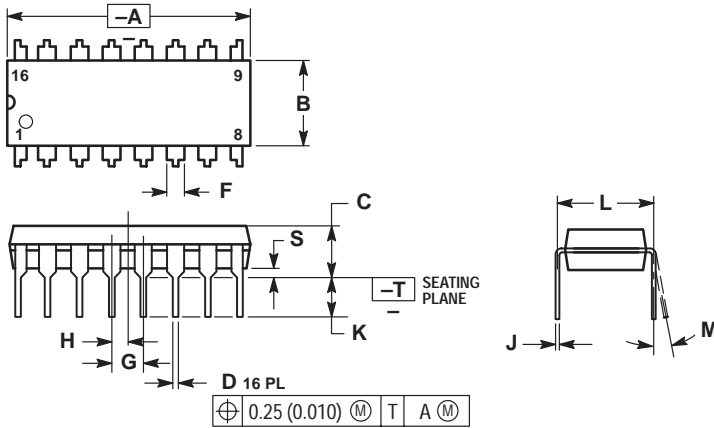
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.070	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

SOIC–16
D SUFFIX
CASE 751B–05
ISSUE J
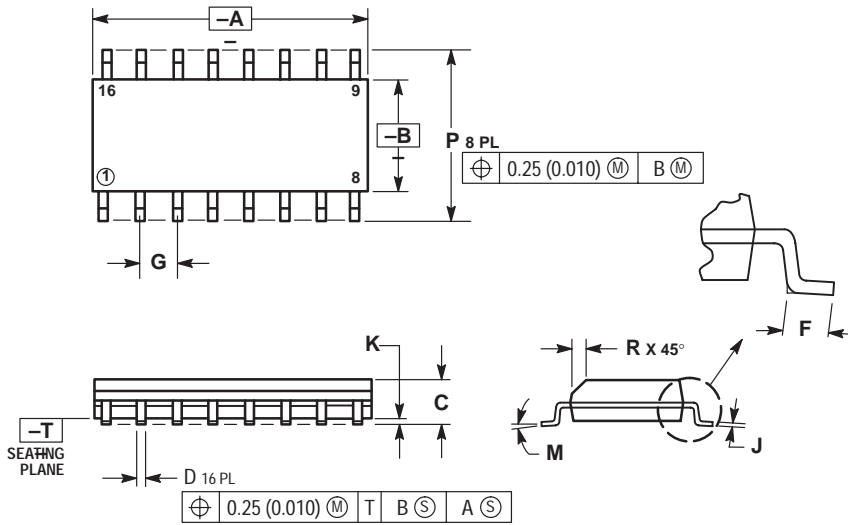
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

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PACKAGE DIMENSIONS

TSSOP–16
DT SUFFIX
CASE 948F–01
ISSUE O
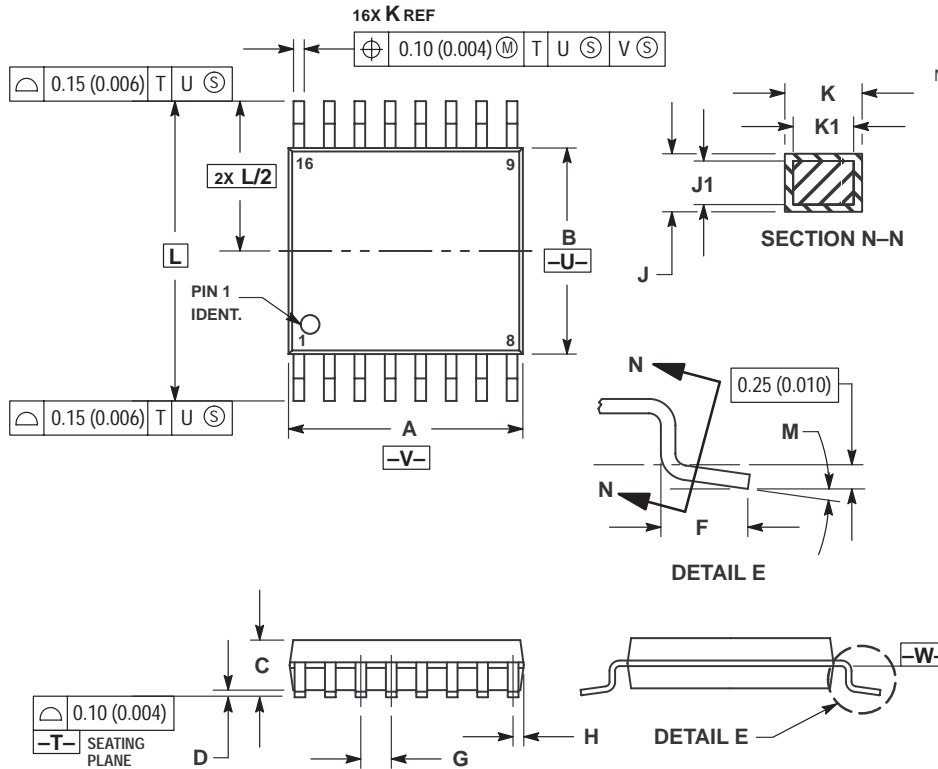
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	–––	1.20	–––	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0 °	8 °	0 °	8 °

SECTION N–N

DETAIL E

DETAIL E

SEATING PLANE

PUBLICATION ORDERING INFORMATION